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TORAY CO., LTD., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 2990108 (JP). **MINE, Katsutoshi** [JP/JP]; 7-20-2, Aobadai, Ichihara-shi, Chiba, 2990117 (JP).

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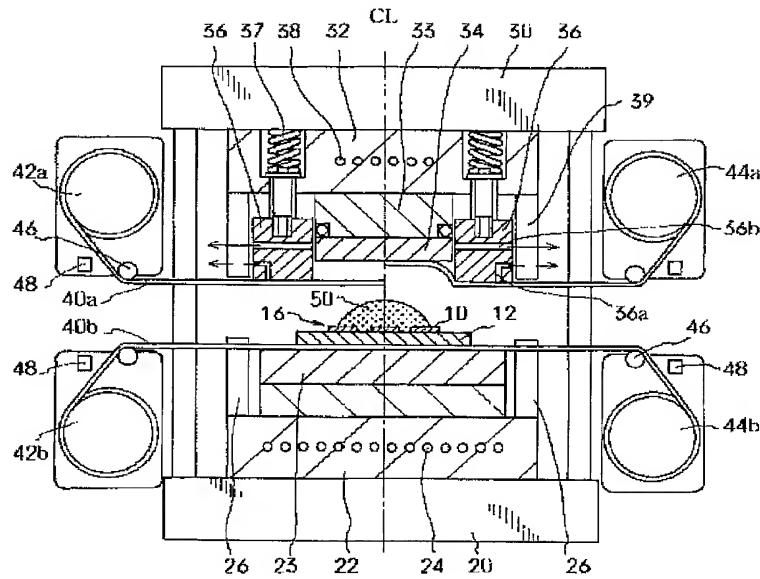
(71) *Applicant (for all designated States except US): DOW CORNING TORAY CO., LTD. [JP/JP]; 1-3, Marunouchi 1-chome,, Chiyoda-ku,, Tokyo1000005 (JP).*

(72) **Inventors; and**
(75) Inventors/Applicants (for US only): MORITA, Yoshitsugu [JP/JP]; c/o DOW CORNING TORAY CO., LTD., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 2990108 (JP). NAKANISHI, Junii [JP/JP]; c/o DOW CORNING

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(54) Title: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THEREOF



(57) Abstract: A method of manufacturing a semiconductor device sealed in a cured silicone body by placing an unsealed semiconductor device into a mold and subjecting a curable liquid silicone composition that fills the spaces between the mold and the unsealed semiconductor device to compression molding under a predetermined molding temperature, wherein the curable liquid silicone composition has viscosity of 90 Pa·s or less at room temperature, a time interval from the moment directly after measurement of a torque with a curometer at the molding temperature to the moment when the torque reached 1 kgf·cm being not less than 1 min., while the time



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